

Sheet 1 of 1							
FORM PTO 1449 (modified)				ATTY DOCKET NO. 2003_1338		SERIAL NO. NEW 10/664,078	
U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE				APPLICANT Mizuki NAGAI et al.			
LIST OF REFERENCES CITED BY APPLICANT(S) (Use several sheets if necessary)				FILING DATE September 17, 2003			
Date Submitted to PTO: September 17, 2003							
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
CW	AA	5,695,810	12/1997	Dubin et al.	427	96	
	AB	6,110,011	8/2000	Somekh et al.	451	28	
	AC	6,197,181	3/2001	Chen	205	123	
	AD	2002-0004301	1/2002	Chen et al.	438	687	
	AE	6,267,853	7/2001	Dordi et al.	204	232	
	AF	6,413,436	7/2002	Aegerter et al.	216	13	
	AG	6,350,364	2/2002	Jang	205	118	
	AH	6,319,387	11/2001	Krishnamoorthy et al.	205	240	
	AI	6,251,235	6/2001	Talieh et al.	204	220	
		2002-0033340	3/2002	Cheung et al.	205	101	
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
CW	AJ	00/32835	6/2000	WIPO	—	—	
	AK						
	AL						
	AM						
OTHER DOCUMENT(S) (Including Author, Title, Date, Pertinent Pages, Etc.)							
CW	AO	Akihisa HONGO et al., "WAFER CLEANING APPARATUS", U.S. Patent Application Serial No. 09/572,432, filed May 17, 2000. USP 6,615,854					
CW	AP	Matsushita, Shinji, "Copper Electroplating Apparatus 'PARAGON' of Semitool, Loaded with Seed Layer Measuring Function, Seed Layer Strengthening/Repair Function", and, "Process Single Wafer Measuring Function", Semiconductor FPD World, vol. 19(10), pp. 122-124, Pressjournal (2000). <u>namath</u>					
	AQ						
EXAMINER <u>Edna Wang</u>				DATE CONSIDERED 1/6/05			

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MP
EP 609: Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.